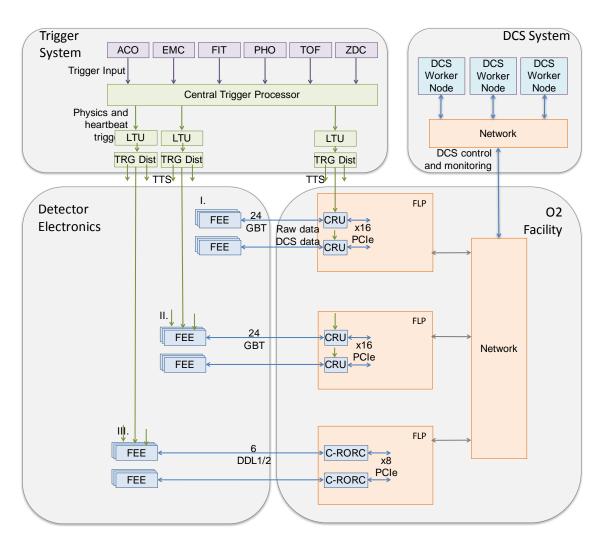
HMPID Trigger during Run3

HMPID Plenary Meeting 14/12/2018

J.L. Gauci University of Malta

Triggering in Run3



- CTP will produce trigger signals
 - LM, L0, L1 with several latencies
- In addition CTP will produce the HB trigger and other software triggers.
- All trigger types are sent via LTU and TTS

HMPID in Run3

• HMPID Requirements:

- LO signal at ~1.2 us after an event when charge on the pads is at its peak
- Message to be able to assemble header for data transfer
- Run3 triggering for detectors with TTC System
 - One synchronous trigger via channel A, sent at LM, L0 or L1 time
 - An asynchronous message in channel B, containing the trigger data sent from CTP at L1 time
- HMPID will also receive an LM trigger via LVDS cables

HMPID in Run3

Why LM?

- L0 signal arrives at CTP at 1200 us
- It arrives at our detector (over TTC) at ~1.7 us, which would be too late for us
- Solution is to use LM which arrives at the detector at ~835 ns

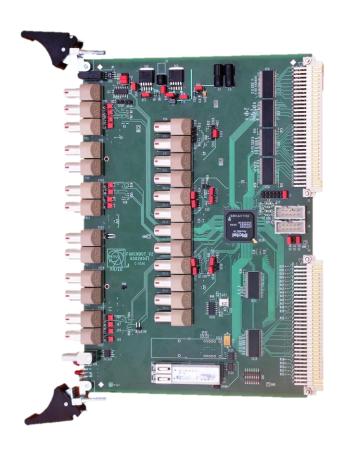
Time	Total Latency (ns)	Description
$425\mathrm{ns}$	$425\mathrm{ns}$	LM input to CTP board
$100\mathrm{ns}$	$525\mathrm{ns}$	CTP Processing Time
$125\mathrm{ns}$	$650\mathrm{ns}$	CTP-LTU Fan-Out Time
$25\mathrm{ns}$	$675\mathrm{ns}$	LTU Processing Time
$160\mathrm{ns}$	$835\mathrm{ns}$	Propagation Time from LTU to HMPID

Table: Calculating the propagation time of LM via LVDS

HMPID in Run3

- Upgrades to HMPID are twofold:
 - 1. New Fan-In/Fan-Out module for precise control on the delay, distribution of LM and fan-in of BUSY
 - 2. Upgrades of Firmware to handle trigger message

Fan-In/Fan-Out Module



Current Module:

• Delay Range: 2.5 us

• Delay Resolution: 25 ns

Improved Module

• Delay Range: 525 ns

• Delay Resolution: 1 ns

Design and Implementation

- Tapped Shift Register Based Architecture with a multiplexer.
- Implementation in Xilinx Virtex 5 FPGA

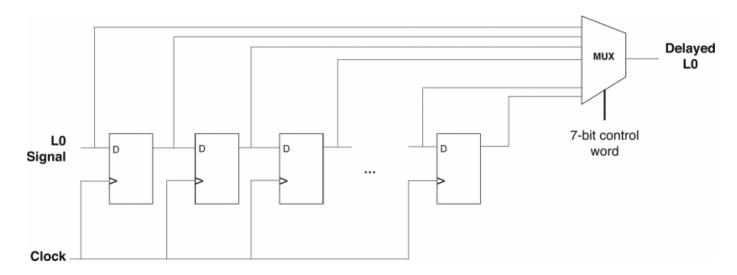
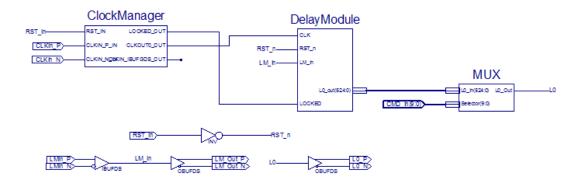
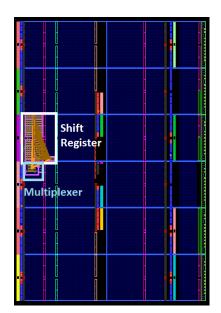


Figure: Implementation of Digital Delay Line

Design and Implementation

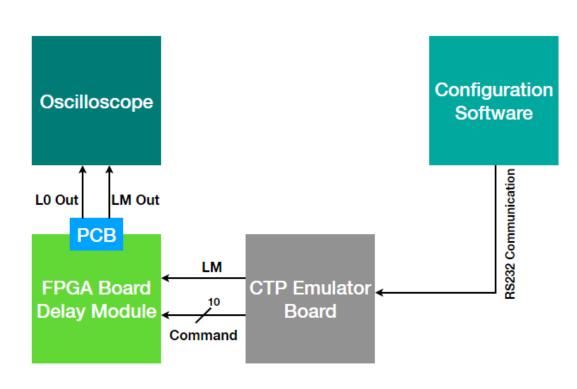




- ClockManager 1 GHz Clock Generator
- Delay Module Shift Register
- MUX Multiplexer

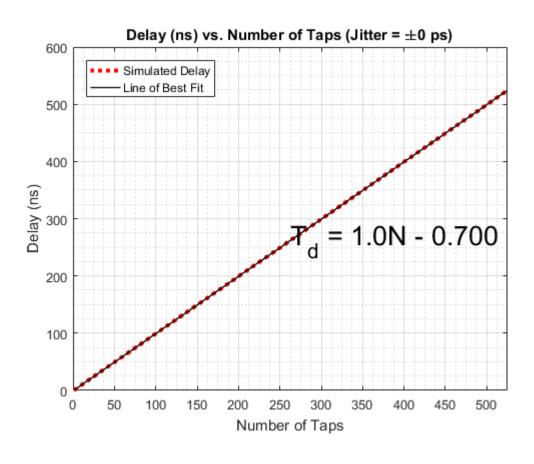
 Floorplanning to constrain occupied area by the Shift Register

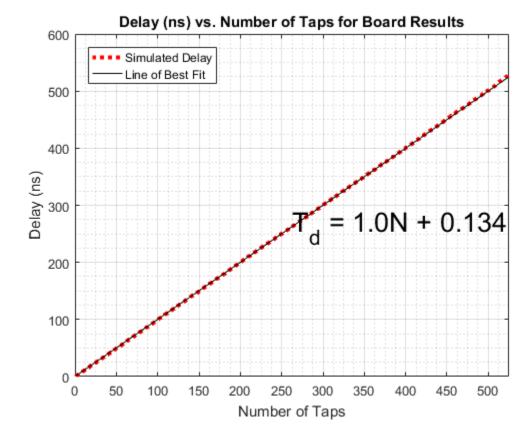
Testing





Results

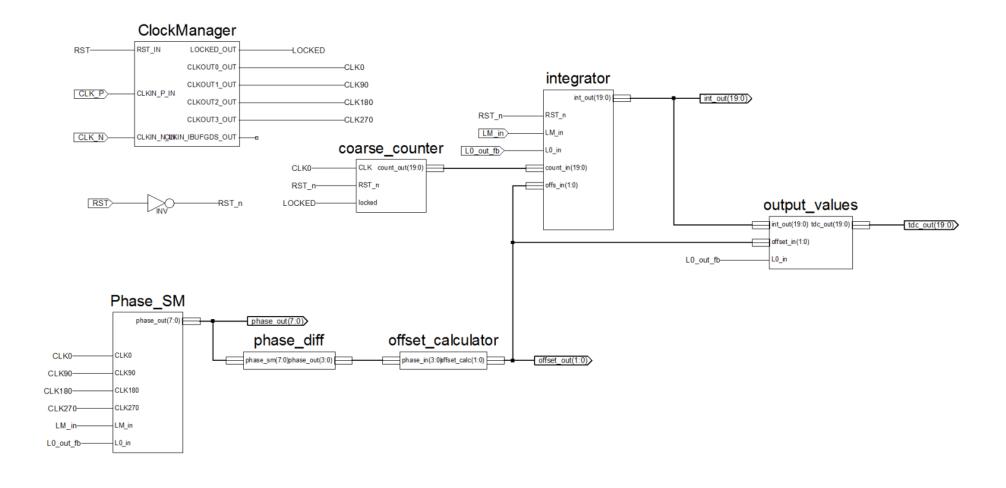




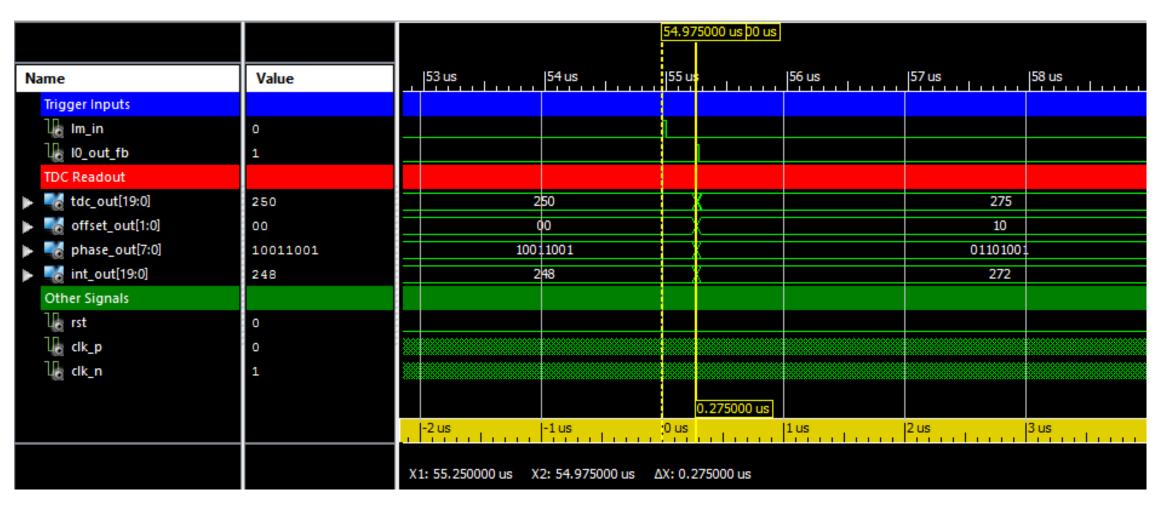
Monitoring Module

- Problem with this delay line is that there is an unpredictable offset.
 - Stems from the accumulation of jitter along the line
- One Solution is to use a control loop to monitor the delay and correct the multiplexer code, if the delay is more than +/- 1 ns

Monitoring Module



Monitoring Module - Results



Firmware Upgrades

- Tests in Bld 581 on present Firmware were performed by Raul and myself
- Problem with v27 VHDL conversion of header module
 - Solved by changing header block to AHDL
 - No more corrupted header received
- Problem with errors in hardware?
 - Yes and No. Most probably what is resulting in errors from TB is the fact that we are running firmware from P2
- New Firmware so far:
 - Changed from unreliable reset module clock to one generated by PLL
 - Started new TTC module

New TTC Module Run3

- Writing of new TTC module for Run3 underway
- Data Format for Run3

Data	Word Number	Payload	Content
[015]	x	TType[015]	Trigger Type
[011]	x	BCID[011]	BCID
[015]	x	Orbit[015]	Orbit Low
[015]	x	Orbit[1631]	Orbit High

 $63\ 62\ 61\ 60\ 59\ 58\ 57\ 56\ 55\ 45\ 3\ 52\ 51\ 50\ 49\ 48\ 47\ 46\ 45\ 44\ 43\ 42\ 41\ 40\ 39\ 38\ 37\ 36\ 35\ 34\ 33\ 32\ 31\ 30\ 29\ 28\ 27\ 26\ 25\ 24\ 23\ 22\ 21\ 20\ 19\ 18\ 17\ 16\ 15\ 14\ 13\ 12\ 11\ 10\ 9\ 8\ 7\ 6\ 5\ 4\ 3\ 2\ 1\ 0$



HB or Physics trigger

New TTC Module for Run3

- Handles LO, L1 sequence
- Handles HB Trigger even when BUSY
- Header Builder by filling in respective values of the CDH

 No way of testing this so far as I cannot build a fake trigger message using the CTP Emulator.

Plans for 2019

January 2019

- We should have the new lab completed with Run3 LTU and C-RORC.
 - In this way we can test the various functionalities of the new firmware.
- Tests at P2 of porting to VHDL (Run2 environment)
- Final Design and Prototype of Fan-In/Fan-Out Module
- Final Prototype of Run3 Firmware